

INTERNATIONAL SINGULATION EQUIPMENT PROVIDER DIRECTORY

Company Address ☎ Phone 🏠 Year Founded ★ President ◆ CEO ◇ Other Title	Model Name/Model # ☒ Machine Size (LxWxH, in meters)	☒ Level of Automation ⚙ Singulation Method: Laser, Saw, Scribe or Other ● Largest Substrate (LxW in mm)	☑ Applications 1=Hard Materials Dicing 2=IC Dicing 3=Opto 4=Package Singulation 5=Wafer Preparation 6=Thin-Wafer Dicing ◎ Special or Unique Features	Web Site ❄ Customer Contact 🌐 Other Offices <i>Editor's Notes: CM=Consult Manufacturer. Listings were supplied by the vendors. Advertisers are shown in Boldface type.</i>
Disco Hi-Tec America Inc. 3270 Scott Blvd. Santa Clara, CA 95054 ☎ 408.987.3776 🏠 1937 ◇ Nobukazu Dejima (Exec. VP)	DISCO Singulation Engine Model EAD685/695 ☒ 1.320 x 1.335 x 1.235	☒ Fully automated ⚙ Saw ● 250 x 250mm	☑ CM	discousa.com ❄ Catherine Spellis info@discousa.com 408.987.3776
Greatech Automation (M) Sdn Bhd Plot 287B Lengkok Kampung Jawa Satu, Phase 3 Bayan Lepas Free Industrial Zone, 11900 Penang, West Malaysia ☎ +6.04.6463260 ★◆ Tan Eng Kee	BDH 9000 Tapeless/Nestless Dicing Handler System ☒ 2.0 x 1.5 x 1.4	☒ Automated ⚙ Saw ● 250 x 70mm	☑ 1, 2, 3, 4, 5 ◎ Low operating cost, tapeless/nestless	greatech-group.com ❄ Richard Ong, Business Manager richong@tm.net.my 408.987.3776
Han-Mi Co. Ltd. 533-3 Kajwa-Dong, Seo-Ku Incheon, Korea ☎ +82.32.577.9751 ◇ E.K. Tan (Managing Director)	101 CSP Singulation ☒ 2.5 x 1.32 x 1.7	☒ Automated ⚙ Punch ● 250 x 70mm	☑ 4, CM	hanmisemi.com ❄ Mike Kim, Overseas Sales & Marketing mike@hanmisemi.com
	2000 Sawing and Placement ☒ 1.7 x 1.5 x 1.4	☒ Automated ⚙ Saw ● 230 x 70mm	☑ 4, CM	

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<p>Intercon Technology Inc. 18255 Sutter Blvd. Morgan Hill, CA 95037</p> <p>☎ 408.778.5992</p> <p>🏠 1986</p> <p>★ Kim Tan</p> <p>◇ Chris Winkler (Director of Sales & Mktg.)</p>	<p>SBS-8808 Matrix Array Singulation System</p> <p>☒ 1.33 x 1.16 x 1.23 (Stand-alone, will vary with saw engine)</p>	<p>☑ Automated</p> <p>🔍 Saw</p> <p>● 250 x 85mm</p>	<p>☑ 1, 2, 3, 4</p> <p>◎ Advanced design for high throughput >10K UPH, enhanced multi- lingual GUI</p>	<p>intercontechnology.com</p> <p>✳ Chris Mihai, Senior Applications Engineer cmihai@intercontechnology.com</p>
<p>Meco Equipment Engineers B.V. (BESI Singulation) Marconilaan 2, 5151 DR Drunen the Netherlands</p> <p>☎ +31.416.384.384</p> <p>🏠 1979</p> <p>◇ J. Rischke (Managing Director)</p>	<p>MISS Single Spindle MISS Double Spindle</p> <p>☒ 2.0 x 1.5 x 2.0</p>	<p>☑ Automated</p> <p>🔍 Saw</p> <p>● 254 x 75mm</p>	<p>☑ 1, 2, 3, 4, 5</p> <p>◎ Upside-down sawing, closed-loop post alignment</p>	<p>meco.nl</p> <p>✳ BESI USA Los Gatos, Calif. Rob Cole, Sales Mgr. ficoca@aol.com</p>
<p>Manufacturing Technology Inc. (MTI) 2226 Goodyear Ave. Ventura, CA 93003</p> <p>☎ 805.644.9681</p> <p>★◆ Michael Cromer</p>	<p>NSX-250DSi Dual Spindle Saw</p> <p>☒ 1.42 x 1.44 x 1.57</p>	<p>☑ Semi-Automated</p> <p>🔍 Saw</p> <p>● 250 x 250mm</p>	<p>☑ 1, 2, 3, 4</p> <p>◎ Multi-blade gang saw, 250mm x 250mm XY trvel/spindle</p>	<p>mtionline.com</p> <p>✳ Bill Abeyta, Asia- Pacific Sales Manager babeyta@mtionline.com</p>
<p>Primeca Pte Ltd. 36 Changi South Street 1 Singapore 486766</p> <p>☎ +65.6546.2775</p>	<p>8430s</p> <p>☒ 1.3 x 1.2 x 1.5</p>	<p>☑ Automated</p> <p>🔍 Saw</p> <p>● 250 x 80mm</p>	<p>☑ 4</p> <p>◎ Dual substrate stage, handling, dual blade rocking system</p>	<p>primeca.com</p> <p>✳ Lua Kim Teng, VP-Sales luakimteng@primeca.com</p>
<p>Synova S.A. Chemin de la Dent D'Oche CH-1024 Ecublens, Switzerland</p> <p>☎ +41.21.694.3500</p>	<p>LDS 200 A</p> <p>☒ 1.10 x 1.56 x 1.96</p>	<p>☑ Automated</p> <p>🔍 Laser</p> <p>● 200mm</p>	<p>☑ 1, 2, 3, 4, 5, 6, Edge grinding, wafer drilling, scribing and grooving</p> <p>◎ Automated wafer loading and cleaning</p>	<p>synova.ch</p> <p>✳ Roy Housh, Sales Mgr. housh@synova.ch</p> <p>🌐 U.S. Office: Gemcity Engineering Co. Dayton, OH 937.223.5544</p>
<p>Xsil Ltd. Unit 3, Trinity Enterprise Centre Pearse St., Dublin, Ireland</p> <p>☎ +353.1245.7500</p> <p>◇ Adbian Boyle (CTO) aboyle@xsil.com</p>	<p>Xise300D</p> <p>☒ 1.2 x 1.5 x 1.81</p>	<p>☑ Automated</p> <p>🔍 Laser</p> <p>● 300mm</p>	<p>☑ 2, 6, Multi-product wafers, via drilling for stacked ICs</p> <p>◎ Clean, low-water dicing, flexible CAD input for odd die</p>	<p>xsil.com</p> <p>🌐 Sugar Hill, Georgia</p> <p>✳ Alex Schreiner, Business Development- North America aschreiner@xsil.com</p>